

Title (en)  
SEALING OF A PILING

Title (de)  
ABDICHTUNG EINER SPUNDWAND

Title (fr)  
ETANCHEIFICATION D'UNE CLOISON DE PIEUX

Publication  
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Application  
**EP 05742489 A 20050520**

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Abstract (en)  
[origin: WO2006123009A1] The invention relates to a method for forming a sealed piling in soil of at least two tongue-and-groove elements (1, 6, 18), at least one of which comprises a broaching tool (2). In the method the broaching tool is fastened to the tongue-and-groove element at a distance from the first corner (9) of the tongue-and-groove element, the distance being 0-20 % of the length of a first edge (8) of the tongue-and-groove element. A sealing medium feeding device (13) is fastened to the tongue-and-groove element and the tongue-and-groove element is arranged in the soil and sealing medium (7) is fed by means of the sealing medium feeding device in the cavity created by arranging the broaching tool in the soil. It is characteristic for a typical method for forming a sealed piling according to the invention that the sealing medium feeding device (13) is fastened to the tongue-and-groove element (1, 6, 18) by means of an openable fastening device (37). It is further characteristic for the method according to the invention that the fastening device is released and the sealing medium feeding device is disconnected from the tongue-and-groove element after the tongue-and-groove element is arranged at a desired depth inside the soil. The invention also relates to a tongue-and-groove element for a piling as well as a sealed piling. Further the invention relates to a method for isolating contaminated soil.

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